

REMARKS/ARGUMENTS

Favorable reconsideration of this application, as presently amended and in light of the following discussion, is respectfully requested.

Claims 1-29 are presently pending in this application, Claims 9-29 having been withdrawn from further consideration by the Examiner, Claims 1-8 having been amended by the present amendment.

In the outstanding Office Action, Claims 1-8 were rejected under 35 U.S.C. §112, second paragraph, for being indefinite; and Claims 1-8 were rejected under 35 U.S.C. §102(b) as being anticipated by EP 1117283 (hereinafter “EP ‘283”).

Claims 1-8 have been amended to clarify the subject matter recited therein. Thus, Claims 1-8 are believed to be in compliance with the requirements under 35 U.S.C. §112, second paragraph, and these amendments are believed to find support in the specification, claims and/or drawings as originally filed, for example, Figure 22. No new matter is believed to be added thereby. If, however, the Examiner disagrees, the Examiner is invited to telephone the undersigned who will be happy to work in a joint effort to derive mutually satisfactory claim language.

Briefly recapitulating, Claim 1 of the present invention is directed to a multilayer printed wiring board and recites: “a multilayer core substrate comprising a plurality of insulating layers, a front conductive layer formed on a surface of a front outermost one of the insulating layers, a rear conductive layer formed on a surface of a rear outermost one of the insulating layers, an inner conductive layer formed between the insulating layers, and a plurality of via holes electrically connecting the front, rear and inner conductive layers; an interlayer insulation layer formed over the multilayer core substrate; a conductive layer formed on the interlayer insulating layer and over the multilayer core substrate, wherein at least two of the front, rear and inner conductive layers comprise one of a plurality of power

source conductive layers and a plurality of grounding conductive layers, and the plurality of power source conductive layers or the plurality of grounding conductive layers has thicknesses of which a sum is larger than a thickness of the conductive layer on the interlayer insulation layer.”

It is respectfully submitted that EP ‘283 does not teach or suggest “a multilayer core substrate comprising a plurality of insulating layers, a front conductive layer formed on a surface of a front outermost one of the insulating layers, a rear conductive layer formed on a surface of a rear outermost one of the insulating layers, an inner conductive layer formed between the insulating layers, and a plurality of via holes electrically connecting the front, rear and inner conductive layers ..., wherein at least two of the front, rear and inner conductive layers comprise one of a plurality of power source conductive layers and a plurality of grounding conductive layers, and the plurality of power source conductive layers or the plurality of grounding conductive layers has thicknesses of which a sum is larger than a thickness of the conductive layer on the interlayer insulation layer” as recited in amended Claim 1.

On the other hand, EP ‘283 simply shows a core board 3030, lands 3036a formed on the surfaces of the core board 3030 and a plated-through hole 3036 formed *through and across* the core board 3030. The plated-through hole 3036 provides electrical connection between the lands 3036a formed on the opposite surfaces of the core board 3030. Therefore, the structure recited in Claim 1 is clearly distinguishable from EP ‘283 and is not anticipated thereby. Furthermore, because EP ‘283 fails to disclose the multilayer core substrate as recited in Claim 1, its teachings would not render the structure recited in Claim 1 obvious.

For the foregoing reason, Claim 1 is believed to be allowable. Furthermore, since Claims 2-8 depend directly or indirectly from Claim 1, substantially the same arguments set

forth above also apply to these dependent claims. Hence, Claims 2-8 are believed to be allowable as well.

In view of the amendments and discussions presented above, Applicants respectfully submit that the present application is in condition for allowance, and an early action favorable to that effect is earnestly solicited.

Respectfully submitted,

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A handwritten signature in black ink, appearing to read 'Akihiro Yamazaki', is written over a horizontal line.

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